

Supplementary Information: Batch fabrication of microelectrode arrays with glassy carbon microelectrodes and interconnections for neurochemical sensing: promises and challenges

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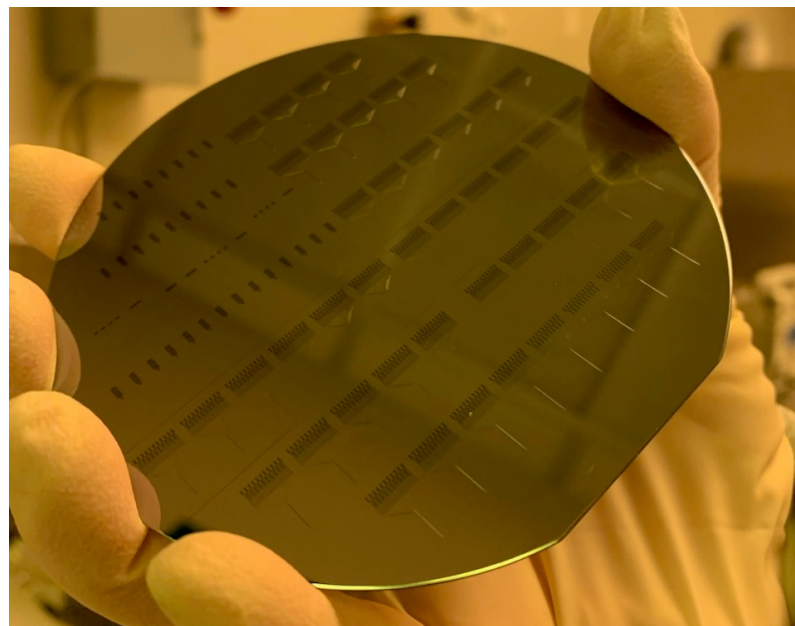


Figure S1. GC microelectrode and interconnection on a 4-inch wafer. Different MEA layouts were incorporated into the same photomasks to test different trace spacing (10 to 20 μm), microelectrode center-to-center distances (100 to 250 μm), microelectrode shape (30 to 40 μm diameter circular or 55 x 25 μm oval) and microelectrode numbers (5 to 8), shank width (90 to 140 μm).

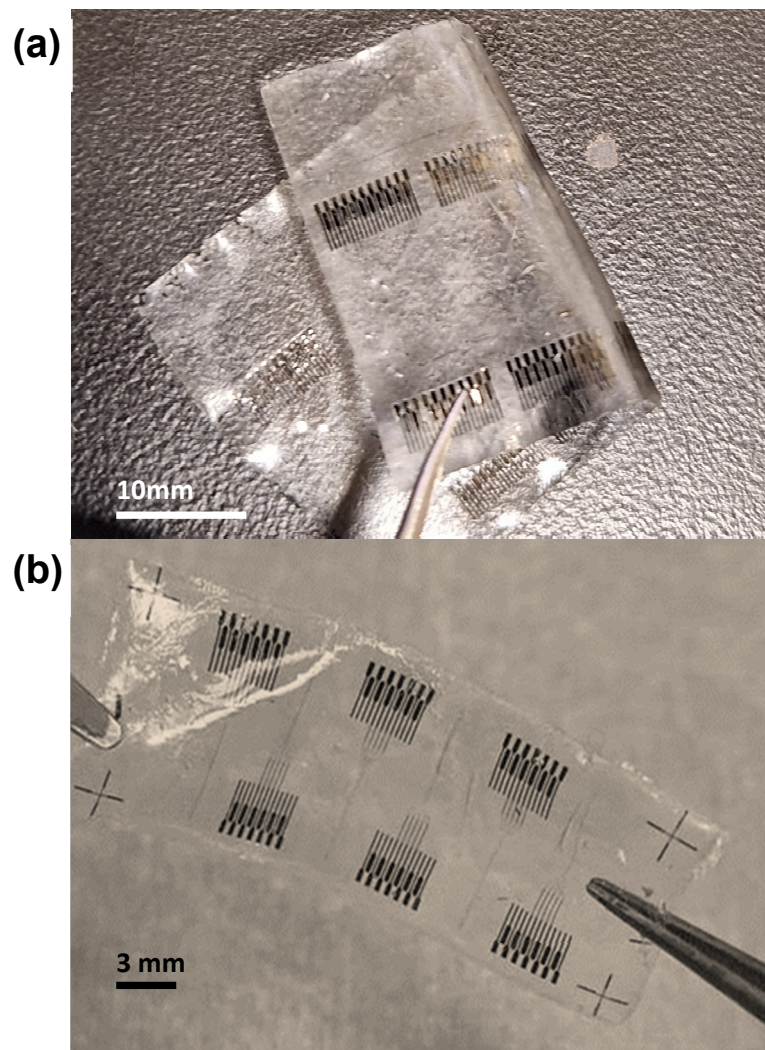


Figure S2. Double Pattern Transfer Fabrication: (a, b) optical images of two standalone PDMS layers (300 μm thick) containing the transferred all GC-MEAs, after being released from the SiO_2 wafer using a chemical buffered oxide etching.